



SOT993-3

HVQFN28: plastic thermal enhanced very thin quad flat package; no leads; 28 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN28
Package type industry code	HVQFN28
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	2-3-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	4.9	-	5	5.1	mm
A	seated height	0.8	-	0.85	1	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	28	-	

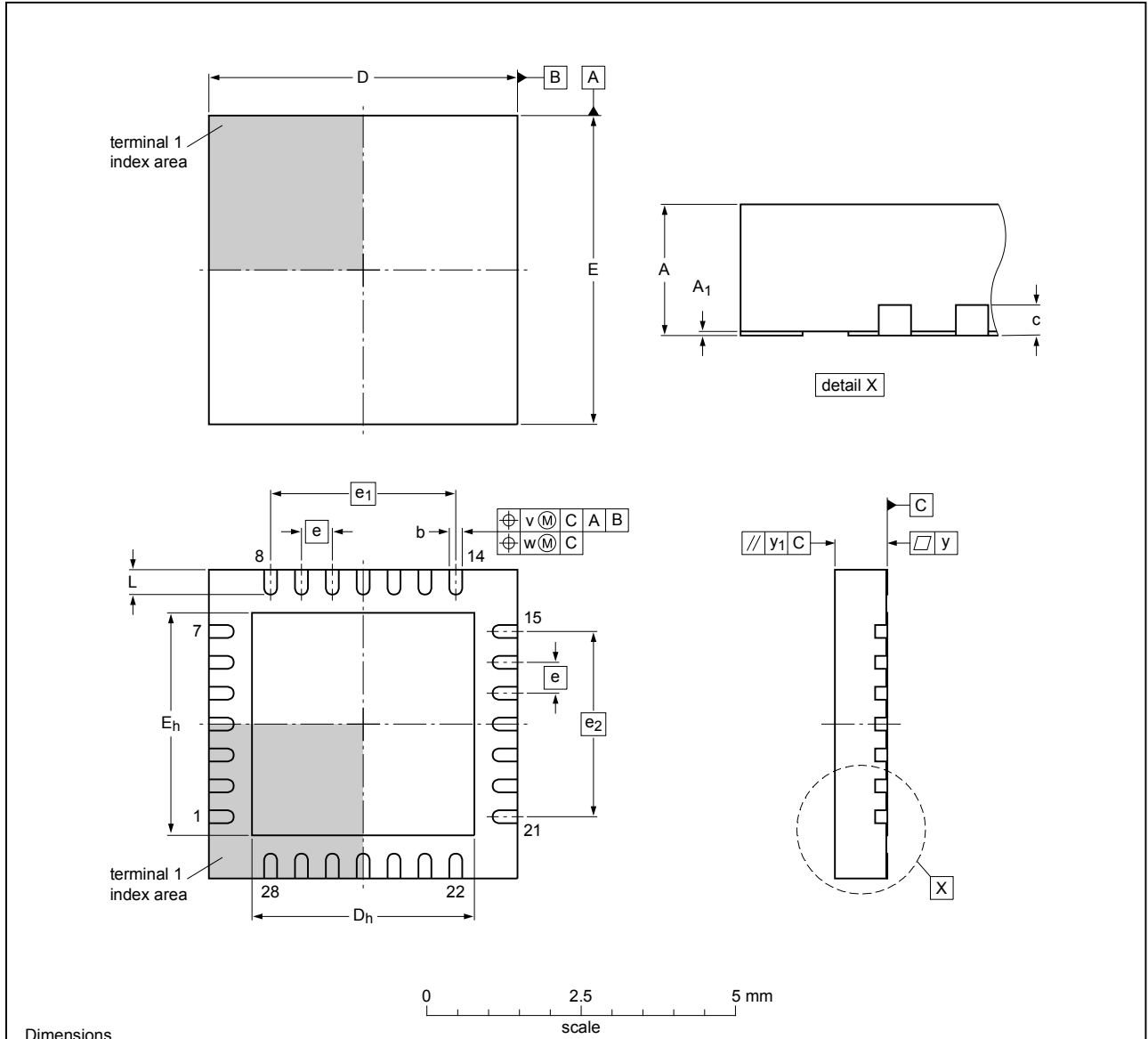


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2. Package outline

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Dimensions

Unit ⁽¹⁾	A	A ₁	b	c	D	D _h	E	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
max	1.00	0.05	0.30		5.1	3.7	5.1	3.7				0.5				
mm nom	0.85	0.02	0.21	0.2	5.0	3.6	5.0	3.6	0.5	3	3	0.4	0.1	0.05	0.05	0.1
min	0.80	0.00	0.18		4.9	3.5	4.9	3.5				0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot993-3_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT993-3		MO-220	---		10-01-14 10-03-02

Fig. 1. Package outline HVQFN28 (SOT993-3)

3. Soldering

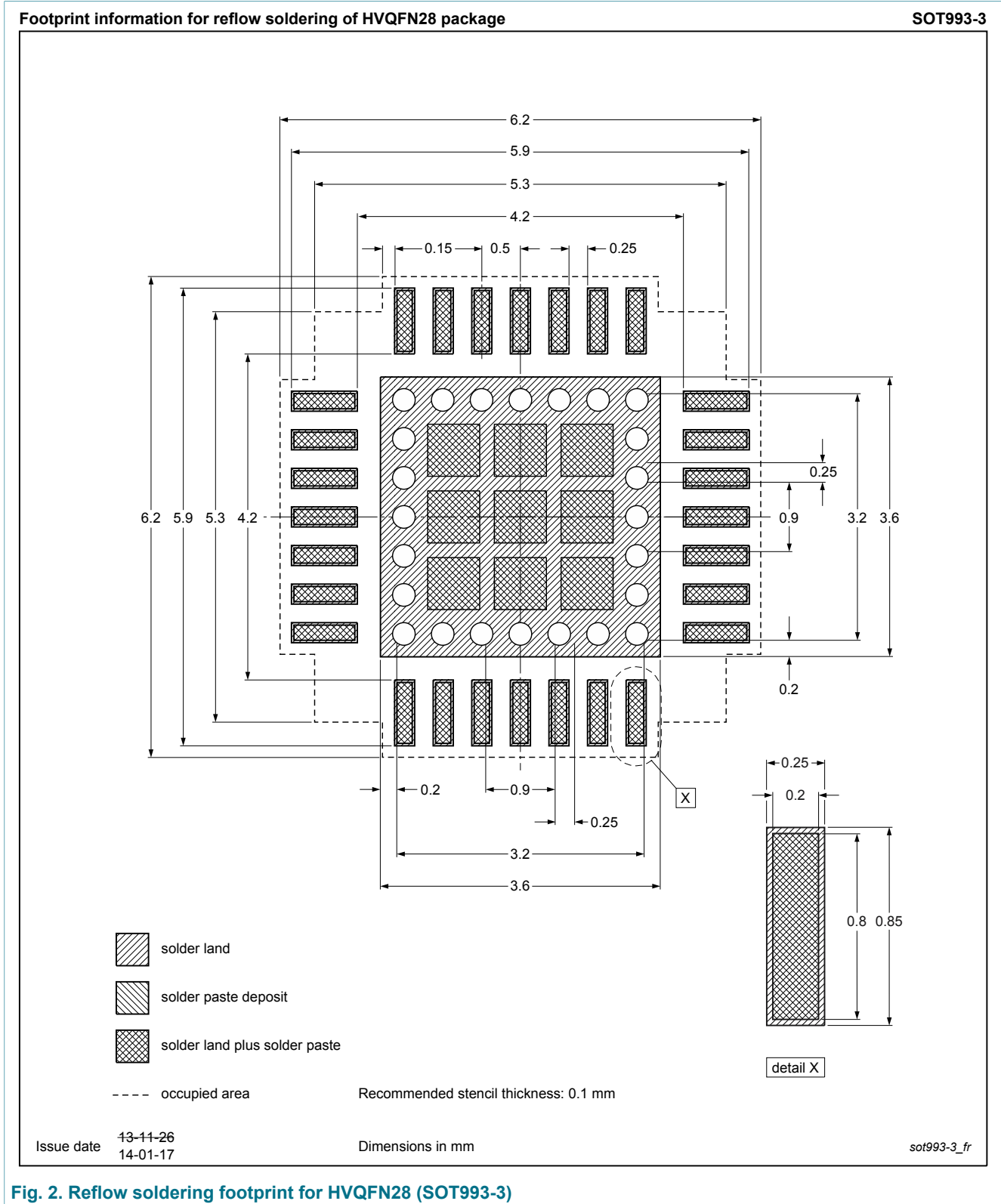


Fig. 2. Reflow soldering footprint for HVQFN28 (SOT993-3)

4. Legal information

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